

## 5 Minute® Epoxy Gel

None

Good solvent resistance

Fills gaps to .250 inches Non-sagging adhesive

**Description:** Thixotropic/non-migrating gel adhesive with excellent gap-filling properties.

Intended Use: Bonding metal, ceramic, wood and vertical surface where gap-filling is needed.

Product features:

Typical

Limitations:

Technical data should be considered representative or typical only and should not be used for specification purposes.

Physical Properties:	Cured 7 days @ 75° F Adhesive Tensile Lap Shear[GBS] Dielectric Strength Gap Fill Impact Resistance Service Temperature Shore Hardness Solids by Volume Specific Volume Tensile Elongation Tpeel Uncured Color Fixture Time	2,500 psi @ 0.010" bondline 440 volts/mils Excellent 6.5 ft.lb./in(2) -40°F to 200°F 80 Shore D 100 23.7 in[3]/lb. 1% 2-3 pli Opaque 10-15 min. @ 72°F	TESTS CONDUCTED Adhesive Tensile Shear ASTM D 1002 Cured Density ASTM D 792 Dielectric Strength, volts/mil ASTM D 149 Compressive Strength ASTM D 695 Cured Hardness Shore D ASTM D 2240			
	Full Cure Functional Cure	12 hrs. 3/4-1 hr. @ 72℉				
	Mix Ratio by Volume	3/4-1 III. @ 72 F 1:1				
	Mix Ratio by Weight	1:1				
	Mixed Density	9.75 lbs/gal.: 1.17 gm/cc				
	Mixed Viscosity	Gel				
	Working Time 4-7 min. [28 gm @ 72°F]					
Surface Preparation:	Clean surface by solvent-wiping any deposits of heavy grease, oil, dirt, or other contaminants. Surface can also be cleaned with industrial cleaning equipment such as vapor phase degreasers or hot aqueous baths. If working with metal, abrade or roughen the surface to significantly increase the microscopic bond area and increase the bond strength.					
Mixing Instructions:	5					

- 2. Using mixing stick included on Dev-tube handle, vigorously mix components for one (1) minute.
- 3. Immediately apply to substrate.
- 50 ML/400ML/490 ML CARTRIDGES
- 1. Attach cartridge to Mark V ™ [50ml] 400ml manual or pneumatic dispensing systems.
- 2. Open tip.
- 3. Burp cartridge by squeezing out some material until both sides are uniform (ensures no air bubbles are present during mixing).
- 4. Attach mix nozzle to end of cartridge.
- 5. Apply to substrate.

## Application 1. Apply mixed epoxy directly to one surface in an even film or as a bead. Instructions: 2. Assemble with mating part within recommended working time.

	3. Apply firm pressure between mating parts to minimize any gap and ensure good contact (a small fillet of epoxy should flow out the edges to display adequate gap fill.)					
	For very large gaps: 1. Apply epoxy to both surfaces 2. Spread to cover entire area OR make a bead pattern to allow flow throughout the joint					
	Let bonded assemblies stand for recommended functional cure time prior to handling.					
	CAPABILITIES: Can withstand processing forces Do not drop, shock load, or heavily load					
Storage:	Store in a cool, dry place.					
Compliances:	None					
Chemical	Chemical resistance is calculated with a 7 day, room temp. cure (30 days immersion) @ 75 F)					
Resistance:	Acetic (Dilute) 10%	Poor	Hydrochloric 10%	Poor		
	Acetone	Poor	Isopropanol	Poor		
	Ammonia	Poor	Kerosene	Excellent		
	Corn Oil	Excellent	Methyl Ethyl Ketone	Poor		
	Cutting Oil	Excellent	Mineral Spirits	Excellent		
	Ethanol	Poor	Motor Oil	Excellent		
	Gasoline (Unleaded)	Excellent	Sodium Hydroxide 10%	Poor		
	Glycols/Antifreeze	Fair	Sulfuric 10%	Poor		
Precautions:	Please refer to the appropriate material safety data sheet (MSDS) prior to using this product. For technical assistance, please call 1-800-933-8266 FOR INDUSTRIAL USE ONLY					
Warranty:	Devcon will replace any material found to be defective. Because the storage, handling and application of this material is beyond our control, we can accept no liability for the results obtained.					
Disclaimer:	All information on this data sheet is based on laboratory testing and is not intended for design purposes. ITW Devcon makes no representations or warranties of any kind concerning this data.					
Order Information:	14240 25 ml DevTube 14265 50 ml Dev-Pak DA052 400 ml cartridge					